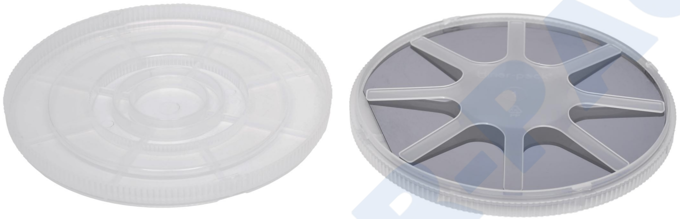
Hiner-pack® SHWS-PP Carrier 150 mm

Durable design safeguards individual wafers from mechanical and environmental damage

In the world of semiconductor wafer shipping, coin-style single wafer shippers are a hallmark of precision and protection. Crafted from see-through natural polypropylene, these single wafer shippers offer an unparalleled blend of security and visibility. The transparent nature of the shippers allows for effortless inspection of the wafer, ensuring integrity during transportation and storage, without the need to open the container, minimizing the risk of contamination and handling damage. This visibility is crucial in maintaining the integrity of wafers throughout their journey, from production facilities to assembly plants, ensuring that each wafer is in perfect condition before use. Our coin-style shippers come in a variety of sizes, including 4" and 6" (customised sizes are available), catering to the diverse needs of the semiconductor industry.

Reference Materials



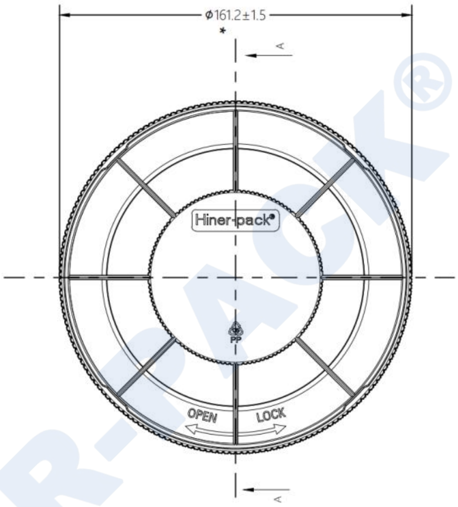
SPECIFICATIONS

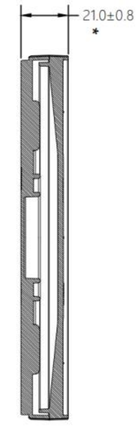
- Φ 161.2 mm × 21 mm H (6.35" × 0.827")
- Maximum load capacity is 1 piece

FEATURES & BENEFITS

- Conical pocket holds one wafer facedown contacting only the wafer’s edge
- Spring retains wafer and minimizes particle generation
- Stackable for efficient use of storage space
- Screw on cover provides secure closure and easy opening
- The enclosed structure minimizes exposure to contaminants
- Large area on cover provides space for labeling

DIMENSION





SECTION A-A

BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
SHWS-6/1-NP	Bottom+Spring+Top	150 mm

REFERENCE ILLUSTRATION

The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183	0.9 g/cm³
Melt Index	ISO 1133	15 g/10min
Melting Point	DSC	146°C
Distortion Temperature	ISO 75	95°C
Vicat softening temperature	ISO 306	125°C
Tensile Strength at Yield	ISO 527	280 kg/m²
Tensile Elongation at Break	ISO 527	300 %
Rockwell hardness R scale	ISO 2039	98
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Modulus	ISO 178	10500 kg/m²
Flow Shrinkage	FPC Method	1.3~1.7 %
LZOD Impact Strength	ISO 180 23°C	6 kg.cm/cm
	-20°C	--- notch

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.